Four-port TeleLink Fuse

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This hybrid Single In-line Package (SIP) protects four twisted pairs from overcurrent conditions. Comprising eight *TeleLink* surface mount fuses, it is ideal for densely populated line cards that connot afford PCB inefficiencies or the use of series power resistors. **0461** .500, **0461** 1.25, **0461** 002. versions are available.

Surge Ratings

TeleLink SM Fuse	l _{PP} 2x10 μs Amps	l _{PP} 10x160 μs Amps	l _{PP} 10x560 μs Amps	Ι _{ΡΡ} 10x1000 μs Amps
F0500Z8 (0461 .500)	not rated	75	45	35
F1250Z8 (0461 1.25)	500	160	115	100
F1251Z8 (0461 002.)	500	160	115	100

Interrupting Values

		I ² t Measured		Interrupting Rating			
TeleLink SM Fuse	Voltage Rating	Current Rating	at DC Rated Voltage	Voltage, Current	MIN	ТҮР	MAX
F0500Z8 (0461 .500)	250 V	500 mA	1.3 A ² s	600 V, 40 A	1 ms	2 ms	60 ms
F1250Z8 (0461 1.25)	250 V	1.25 A	22.2 A ² s	600 V, 60 A *	1 ms	2 ms	60 ms
F1251Z8 (0461 002.)	250 V	2 A	30 A ² s	600 V, 60 A *	1 ms	2 ms	60 ms

* Interrupt test characterized at 50° to 70° phase angle. Phase angles approximating 90° may result in damage to the body of the fuse. Notes:

• The *TeleLink* SM fuse is designed to carry 100% of its rated current for four hours and 250% of its rated current for one second minimum and 120 seconds maximum. Typical time is four to 10 seconds. For optimal performance, an operating current of 80% or less is recommended.

• I²t is a non-repetitive RMS surge current rating for a period of 16.7 ms.

Resistance Ratings

	Typical Voltage Drop DC Cold Resistance		
TeleLink SM Fuse	@ Rated Current	MIN	MAX
F0500Z8	0.471 V	0.420 Ω	0.640 Ω
F1250Z8	0.205 V	0.107 Ω	0.150 Ω
F1251Z8	0.110 V	0.050 Ω	0.100 Ω

Notes:

• Typical inductance < 150 nH up to 500 MHz.

+ Resistance changes 0.5% for every $^\circ\text{C}.$

· Resistance is measured at 10% rated current.

Qualification Data

The F1250Z8 and F1251Z8 meet the following test conditions per GR 1089 **without** additional series resistance. However, in-circuit test verification is required. Note that considerable heating may occur during Test 4 of the Second Level AC Power Fault Test.

First Level Lightning Surge Test

Test	Surge Voltage Volts	Wave-form μs	Surge Current Amps	Repetitions Each Polarity
1	±600	10x1000	100	25
2	±1000	10x360	100	25
3	±1000	10x1000	100	25
4	±2500	2x10	500	10
5	±1000	10x360	25	5

Data Sheets

Second Level Lightning Surge Test

Test	Surge Voltage	Wave-form	Surge Current	Repetitions Each
	Volts	μs	Amps	Polarity
1	±5000	2x10	500	1

First Level AC Power Fault Test

Test	Applied Voltage, 60 Hz V _{RMS}	Short Circuit Current Amps	Duration
1	50	0.33	15 min
2	100	0.17	15 min
3	200, 400, 600	1 at 600 V	60 applications, 1 s each
4	1000	1	60 applications, 1 s each
5	*	*	60 applications, 5 s each
6	600	0.5	30 s each
7	600	2.2	2 s each
8	600	3	1 s each
9	1000	5	0.5 s each

* Test 5 simulates a high impedance induction fault. For specific information, please contact Teccor Electronics.

Second Level AC Power Fault Test for Non-Customer Premises Equipment

Test	Applied Voltage, 60 Hz V _{RMS}	Short Circuit Current Amps	Duration
1	120, 277	30	30 min
2	600	60	5 s
3	600	7	5 s
4	100-600	2.2 at 600 V	30 min

Notes:

• Power fault tests equal or exceed the requirements of UL 60950 3rd edition.

Test 4 is intended to produce a maximum heating effect. Temperature readings can exceed 150 °C.

• Test 2 may be dependent on the closing angle of the voltage source. Fuse is characterized at 50° to 70°. Closing angles approximating 90° may result in damage to the body of the fuse.



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Data Sheets

Temperature Derating Curve

Operating temperature is -55 °C to +125 °C with proper correction factor applied.



Chart of Correction Factor

Maximum Temperature Rise

TeleLink Fuse	Temperature Reading
F0500Z8	≤75 °C (167 °F) *
F1250Z8	≤75 °C (167 °F) *
F1251Z8	≤75 °C (167 °F) *

* Higher currents and PCB layout designs can affect this parameter.

Notes:

· Readings are measured at rated current after temperature stabilizes

 The F1250Z8 meets the requirements of UL 248-14. However, board layout, board trace widths, and ambient temperature values can cause higher than expected rises in temperature. During UL testing, the typical recorded heat rise for the F1250Z8 at 2.2 A was 120 °C.

